

O

G

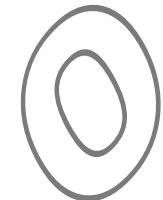
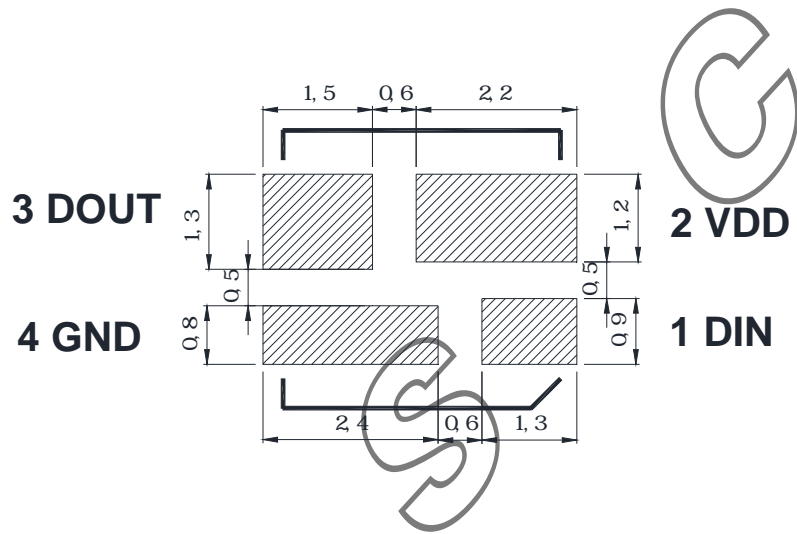
S

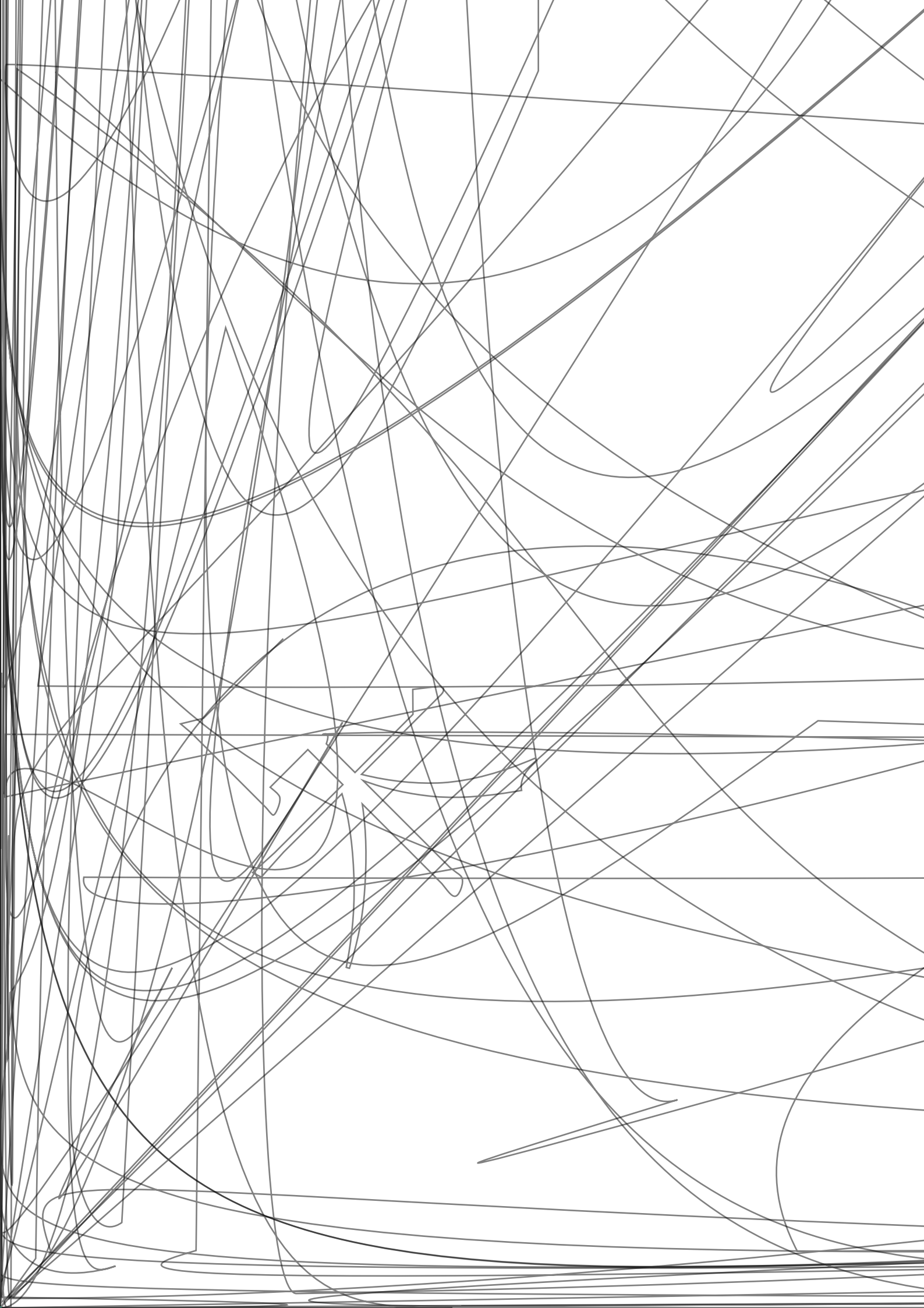
P

O

5.

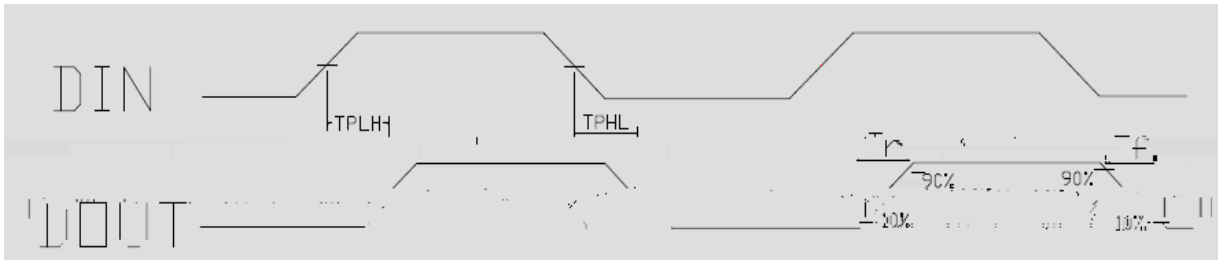
6.





10.

	fDIN					
	T _{PLH}					→



11. :

		Min.		Max.	
T		1.20	--	--	μs
T0H	0	0.2	0.3	0.4	μs
T0L	0	0.8	--	--	μs
T1H	1	0.58	0.64	1.0	μs
T1L	1	0.2	--	--	μs
Trst	Reset	>80	--	--	μs

1.

“ 0 ” “ 1 ”

2.

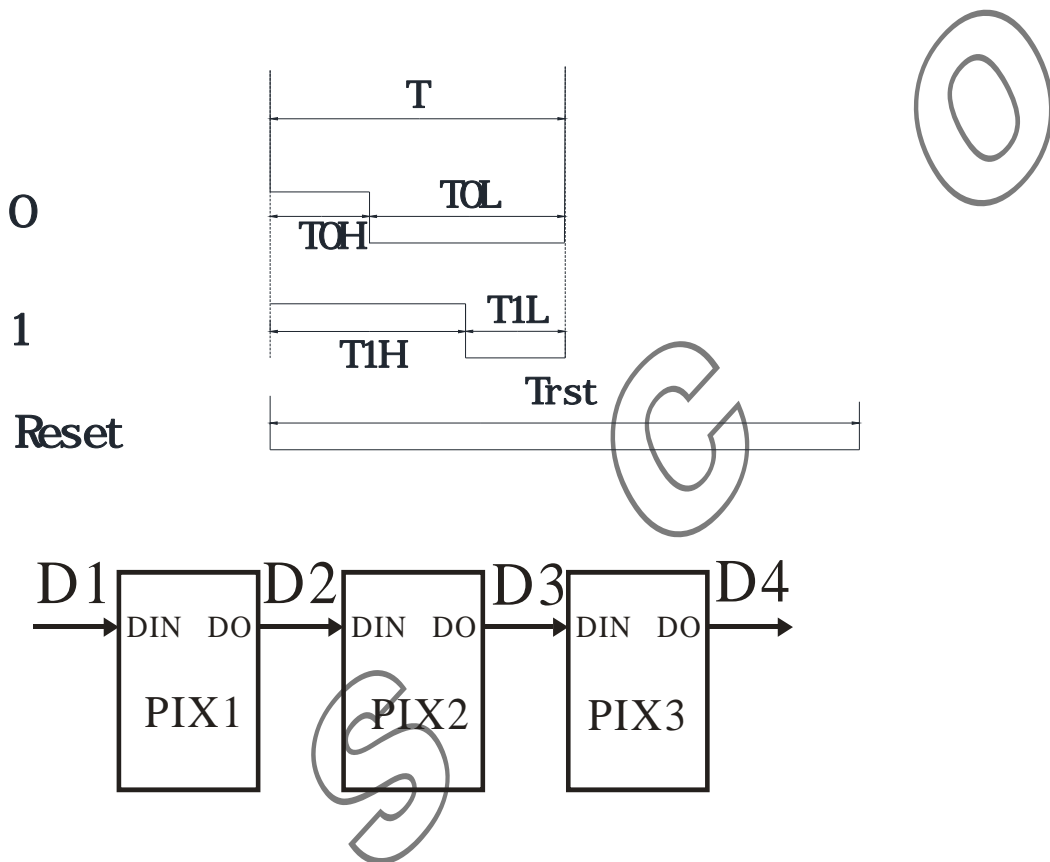
1.2μs

3. “0” “1”

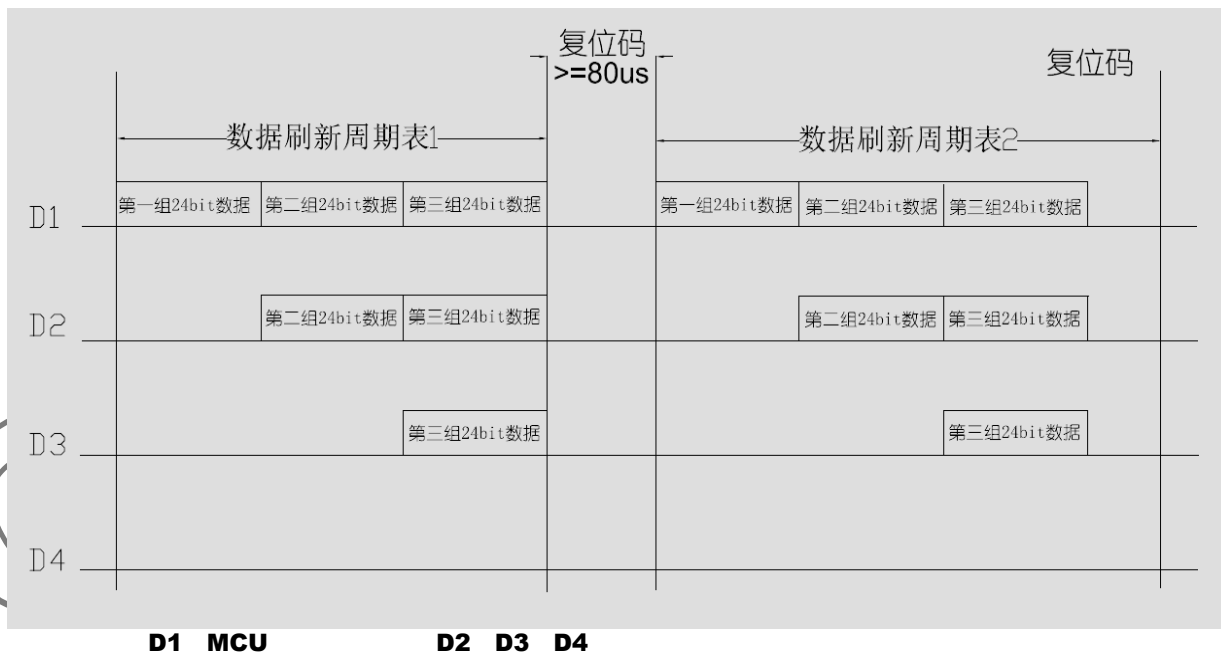
“0” “1”

20μs.

12.



13.



14. 24bit

G7	G6	G5	G4	G3	G2	G1	G0	R7	R6	R5	R4
R3	R2	R1	R0	B7	B6	B5	B4	B3	B2	B1	B0

GRB **(G7 → G6 →.....B0)**

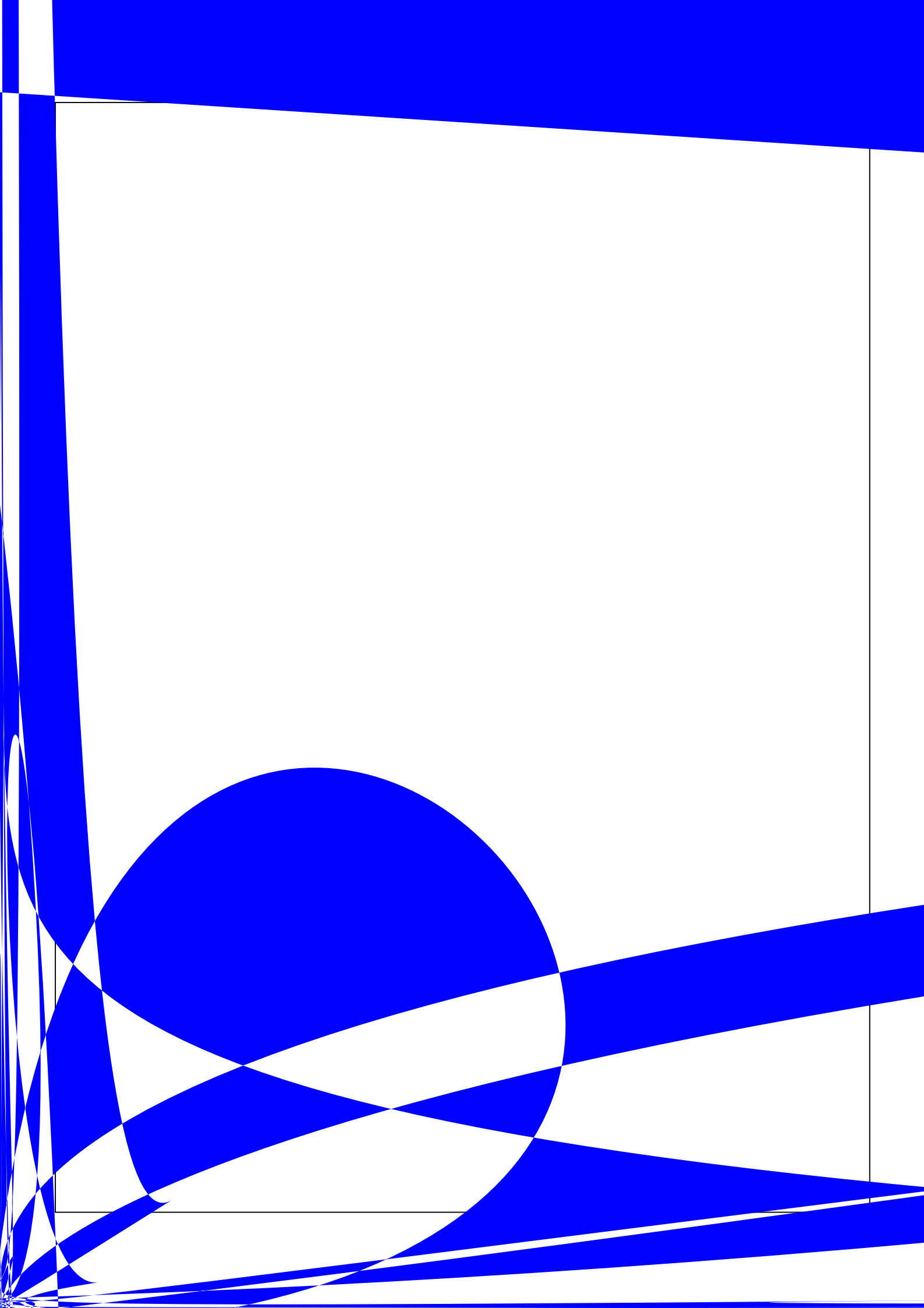
15.



IC

IC

R1

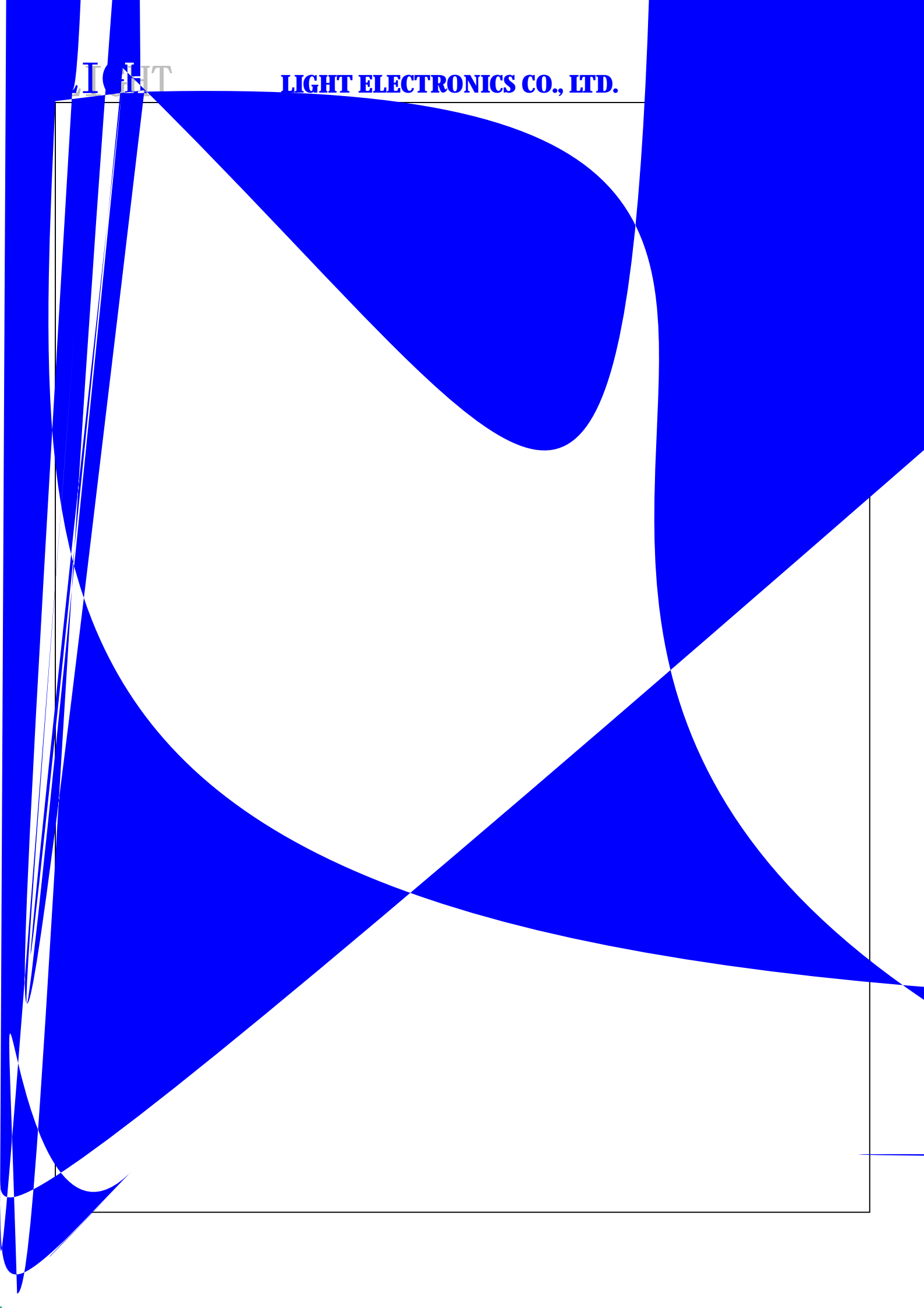




		± ° ° ± °		
		°C 1000hrs		
		°C 1000hrs		
		°C RH=90% 1000hrs		
		-55°C °C °C °C		
		°		
		°		

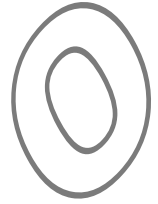
LIGHT

LIGHT ELECTRONICS CO., LTD.



3.3.

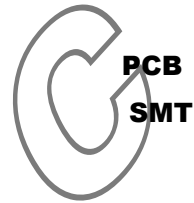
LED SMT
TOP SMD <30 C/60%RH 2



3.4.

0.5H

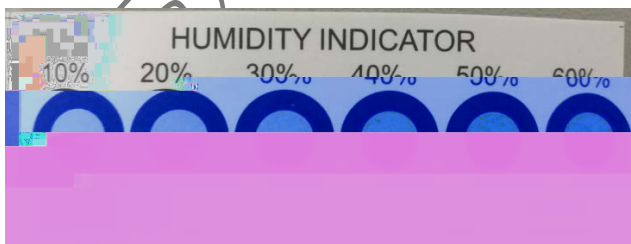
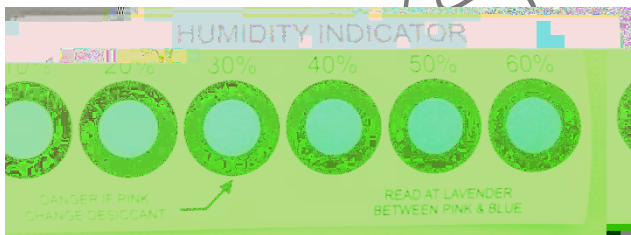
PCB



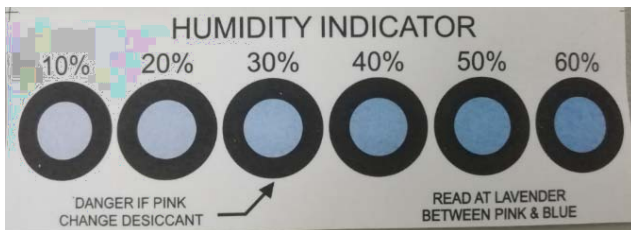
3.5.

TOP SMD LED

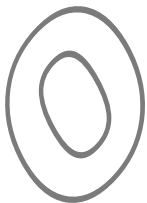
- a. 10% **LED**
- b. 10% 20%
- c. 10% 20% 30%



10% 20%



10% 20% 30%



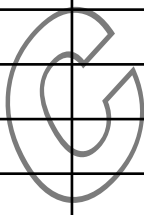
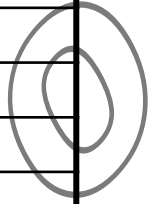
O

P

S

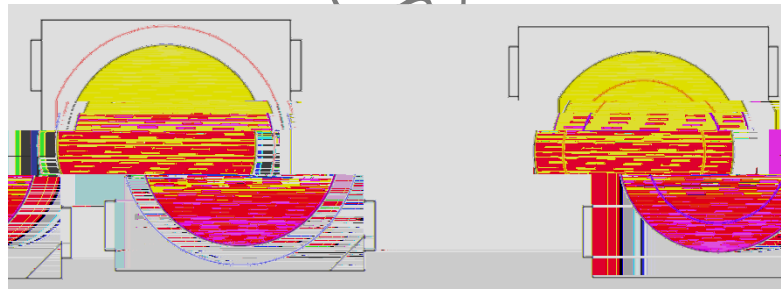
G

x	p	
i		
x		
i	x	
p		



3.8.

. SMT



OK

NG



OK

NG

按压胶体

堆压材

PCB

LED

0.5T
LEDs

PCB

PCB

3.9.

. LED LED PCB LED

. LED LED

. 60 C(60 C,

4.0. IC

. IC LED

. IC

. IC LED LED

.

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. LED .

4.1.

LED LED

LED